
High Performance Sensorless Motor Control IC

Features

- **MCE™ (Flexible Motion Control Engine) - Dedicated computation engine for high efficiency sinusoidal sensorless motor control**
- **Built-in hardware peripheral for single or two shunt current feedback reconstruction and analog circuits**
- **Supports induction machine and both interior and surface permanent magnet motor sensorless control**
- **Loss minimization Space Vector PWM**
- **Two-channel analog output (PWM)**
- **Embedded 8-bit high speed microcontroller (8051) for flexible I/O and man-machine control**
- **JTAG programming port for emulation/debugger**
- **Serial communication interface (UART)**
- **I²C/SPI serial interface**
- **Three general purpose timers/counters**
- **Two special timers: analog watchdog timer, periodic timer, capture timer**
- **Internal 32Kbyte OTP ROM**
- **5V tolerant I/O**
- **3.3V single supply**

Product Summary

Maximum clock input (f_{crystal})	60 MHz
Maximum Internal clock (SYSCLK)	128MHz
Maximum 8051 clock (8051CLK)	32MHz
Sensorless control computation time (max.)	48 μ sec
MCE™ computation data range	16 bit signed
8051 OTP Program ROM (min.)	20KB
805/MCE Data RAM	2KB
MCE Program RAM	12KB
PWM carrier frequency	20 bits/ SYSCLK
A/D input channels	7
A/D converter resolution	12 bits
A/D converter conversion speed	2 μ sec
Analog output (PWM) resolution	8 bits
UART baud rate (typ)	57.6K bps
Number of I/O (max)	10
Package	QFP48
Maximum 3.3V operating current	60mA

Description

IRMCK171 is a high performance One Time Programmable ROM based motion control IC designed primarily for appliance applications. IRMCK171 is designed to achieve low cost yet high performance control solutions for advanced inverted appliance motor control. IRMCK171 contains two computation engines. One is the Flexible Motion Control Engine (MCE™) for sensorless control of permanent magnet motors or induction motors; the other is an 8-bit high-speed microcontroller (8051). Both computation engines are integrated into one monolithic chip. The MCE™ contains a collection of control elements implemented in a dedicated computation engine such as Vector rotator, Arc-Tangent, Multiply/Divide, Low loss SVPWM and Motor current sensing. The user can program a motion control algorithm by connecting Control elements using a graphic compiler. Key components of the complex sensorless control algorithms, such as the Angle Estimator, are provided as complete pre-defined control blocks. A unique analog/digital circuit and algorithm to fully support single shunt current reconstruction is also provided. The 8051 microcontroller performs 2-cycle instruction execution (16.5MIPS at 33MHz 8051CLK). The MCE and 8051 microcontroller communicate via dual port RAM for signal monitoring and command input. An advanced graphic compiler for the MCE™ is seamlessly integrated into the MATLAB/Simulink environment, while third party JTAG-based emulator tools are supported for 8051 software development including an OTP programmer. IRMCK171 comes in a 48 pin QFP package.

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1 Overview

IRMCK171 is a new generation International Rectifier integrated circuit device primarily designed as a one-chip solution for complete inverter controlled appliance motor control applications. Unlike a traditional microcontroller or DSP, the IRMCK171 provides a built-in closed loop sensorless control algorithm using the unique flexible Motion Control Engine (MCE™) for permanent magnet motors as well as induction motors. The MCE™ consists of a collection of control elements, motion peripherals, a dedicated motion control sequencer and dual port RAM to map internal signal nodes. IRMCK171 also employs a unique single shunt current reconstruction circuit in addition to two leg shunt current sensing circuit to eliminate additional analog/digital circuitry and enables a direct shunt resistor interface to the IC. Motion control programming is achieved using a dedicated graphical compiler integrated into the MATLAB/Simulink™ development environment. Sequencing, user interface, host communication, and upper layer control tasks can be implemented in the 8051 high-speed 8-bit microcontroller. The 8051 microcontroller is equipped with a JTAG port to facilitate emulation and debugging tools. Figure 1 shows a typical application schematic using the IRMCK171.

IRMCK171 contains 32K bytes of OTP program ROM, The IRMCF171 contains 64K bytes of Flash RAM and intended for development purposes only while the IRMCK171 is intended for volume production. Both the development and ROM versions come in a 48-pin QFP package with identical pin configuration to facilitate PC board layout and transition to mass production.

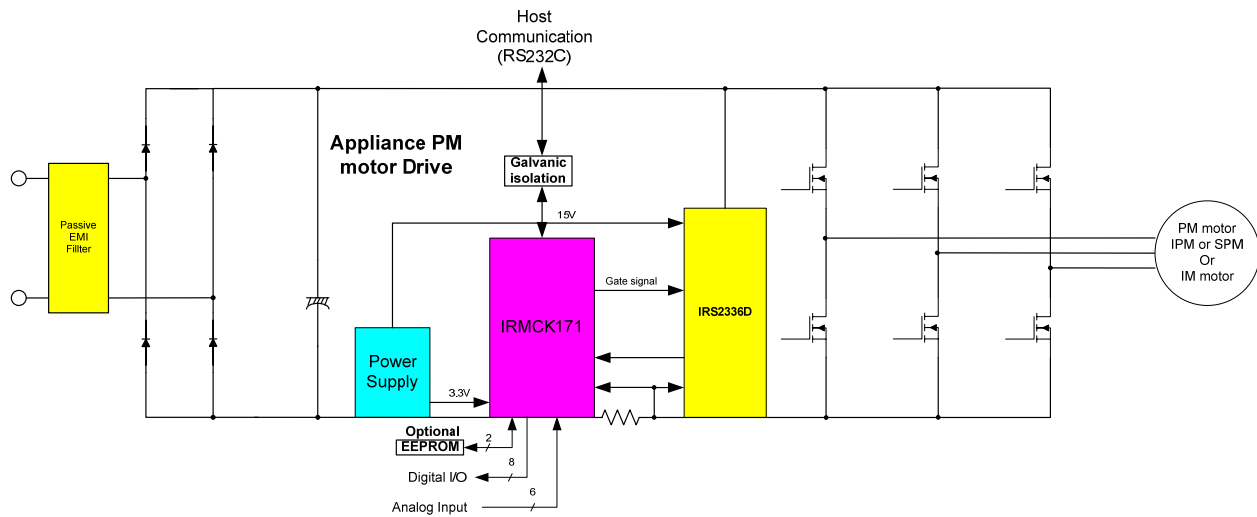


Figure 1 Typical Application Block Diagram Using IRMCK171

2 Pinout

Pin out shown is based on QFP48 pin package.

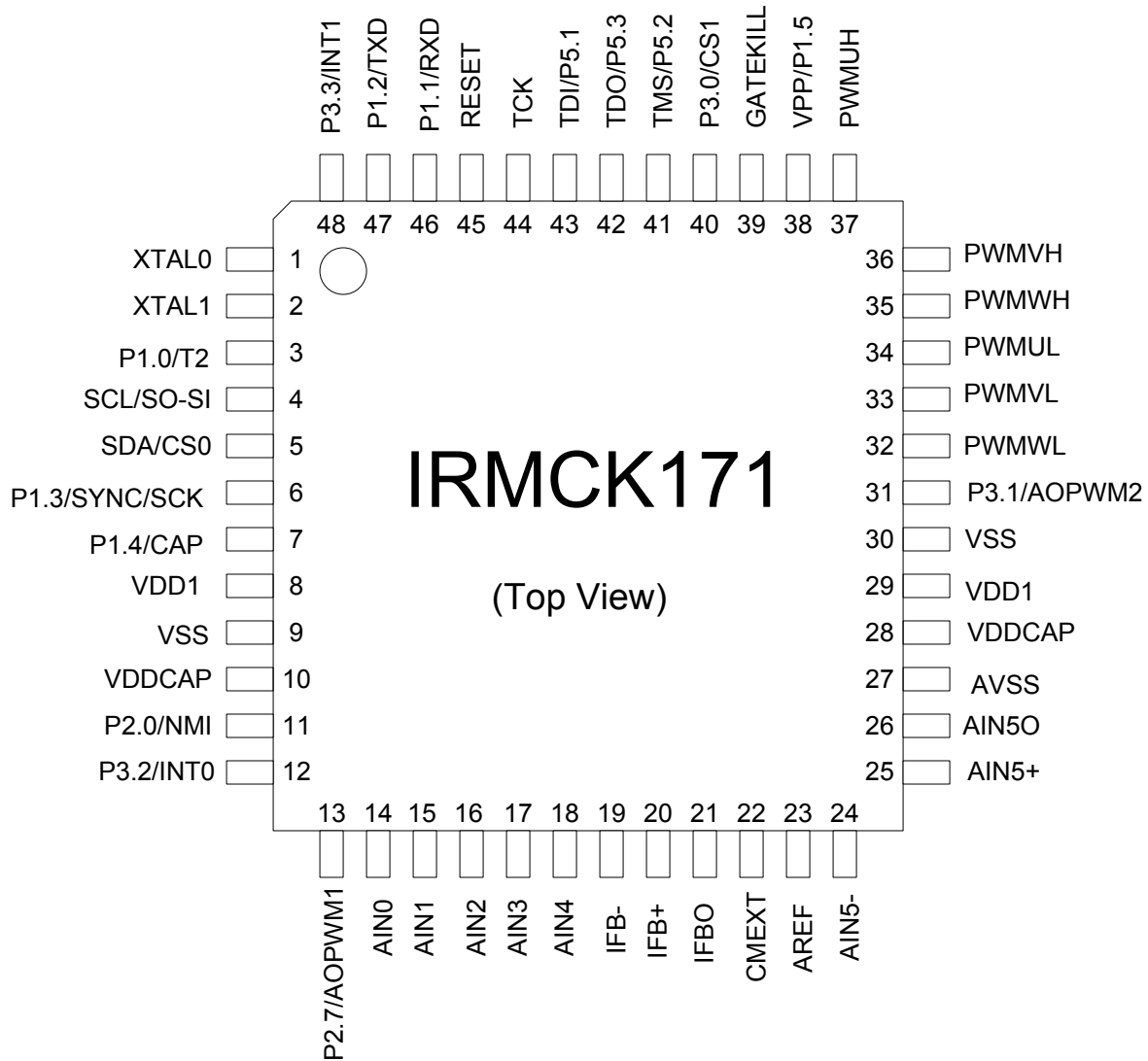


Figure 2 Pinout of IRMCK171

3 IRMCK171 Block Diagram and Main Functions

IRMCK171 block diagram is shown in Figure 3.

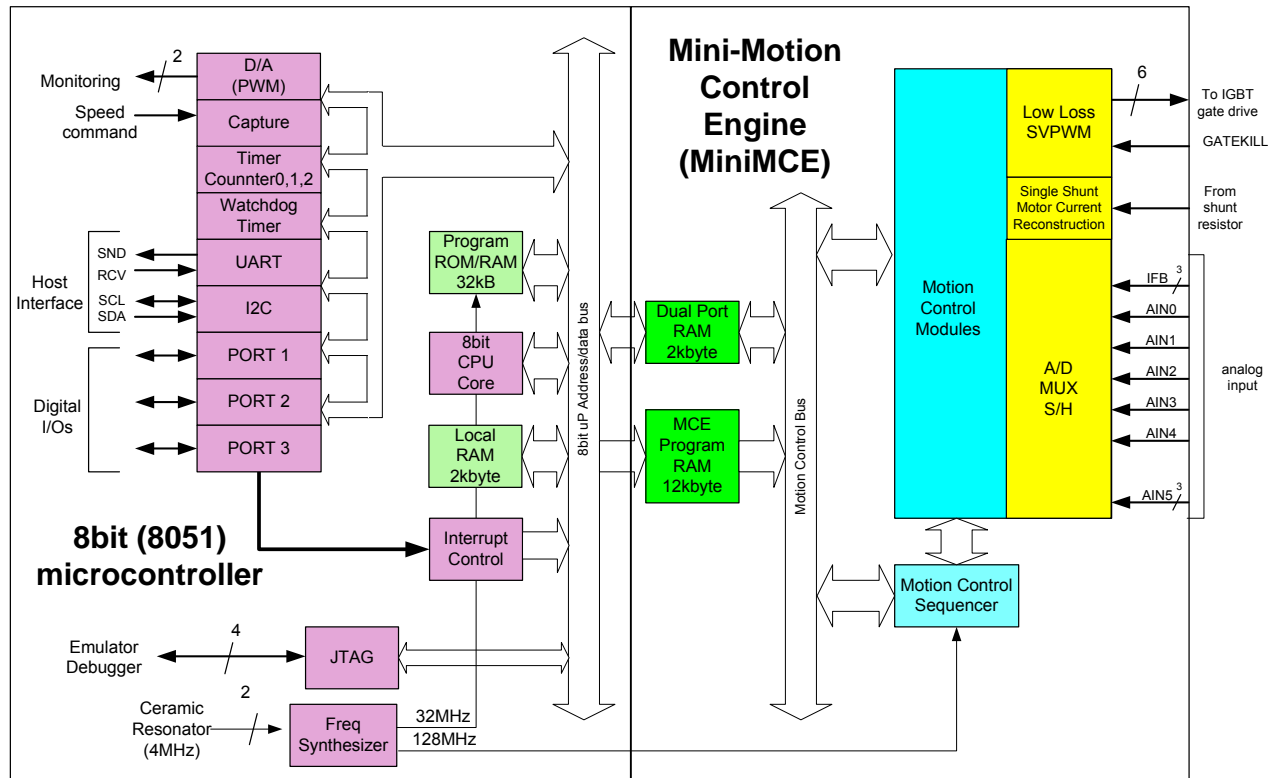


Figure 3 IRMCK171 Block Diagram

IRMCK171 contains the following functions for sensorless AC motor control applications:

- Motion Control Engine (MCE™)
 - Sensorless FOC (complete sensorless field oriented control)
 - Proportional plus Integral block
 - Low pass filter
 - Differentiator and lag (high pass filter)
 - Ramp
 - Limit
 - Angle estimate (sensorless control)
 - Inverse Clark transformation
 - Vector rotator
 - Bit latch
 - Peak detect
 - Transition
 - Multiply-divide (signed and unsigned)

- Divide (signed and unsigned)
- Adder
- Subtractor
- Comparator
- Counter
- Accumulator
- Switch
- Shift
- ATAN (arc tangent)
- Function block (any curve fitting, nonlinear function)
- 16 bit wide Logic operations (AND, OR, XOR, NOT, NEGATE)
- MCE™ program memory and dual port RAM (max 12K+2k byte)
- MCE™ control sequencer
- 8051 microcontroller
 - Two 16 bit timer/counters
 - One 16 bit periodic timer
 - One 16 bit watchdog timer
 - One 16 bit capture timer
 - Up to 24 discrete I/Os
 - Six-channel 12 bit A/D
 - Buffered (current sensing) one channel (0 – 1.2V input)
 - Unbuffered seven channels (0 – 1.2V input)
 - JTAG port (4 pins)
 - Up to three channels of analog output (8 bit PWM)
 - UART
 - I²C/SPI port
 - 32K byte OTP program ROM
 - 2K byte data RAM

4 Application connection and Pin function

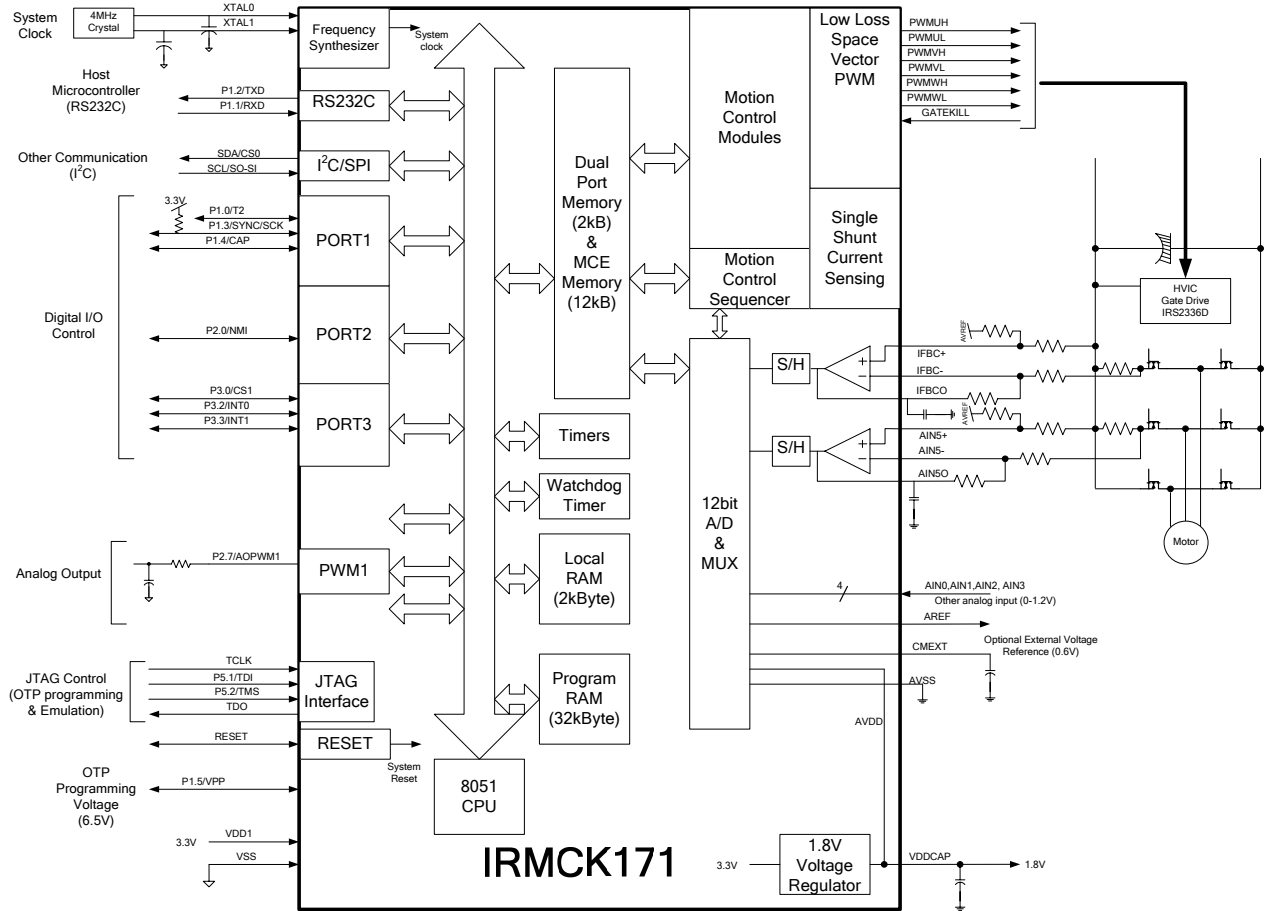


Figure 4 IRMCK171 Connection Diagram

4.1 8051 Peripheral Interface Group

UART Interface

P1.2/TXD	Output, Transmit data from IRMCK171
P1.1/RXD	Input, Receive data to IRMCK171

Discrete I/O Interface

P1.0/T2	Input/output port 1.0, can be configured as Timer/Counter 2 input
P1.1/RXD	Input/output port 1.1, can be configured as RXD input
P1.2/TXD	Input/output port 1.2, can be configured as TXD output
P1.3/SYNC/SCK	Input/output port 1.3, can be configured as SYNC output or SPI clock output, needs to be pulled up to VDD1 in order to boot from I ² C EEPROM
P1.4/CAP	Input/output port 1.4, can be configured as Capture Timer input
P1.5/VPP	Input/output port 1.5, or OTP programming voltage
P2.0/NMI	Input/output port 2.0, can be configured as non-maskable interrupt input
P3.2/INT0	Input/output port 3.2, can be configured as INT0 input
P2.7/AOPWM1	Input/output port 2.7, can be configured as AOPWM1 output
P3.0/INT2/CS1	Input/output port 3.0, can be configured as INT2 input or SPI chip select 1
P3.1/AOPWM2	Input/output port 3.1, can be configured as AOPWM2 output
P3.3/INT1	Input/output port 3.3, can be configured as INT1 input
P5.1/TDI	Input port 5.1, configured as JTAG port by default
P5.2/TMS	Input port 5.2, configured as JTAG port by default

Analog Output Interface

P2.7/AOPWM1	Input/output, can be configured as 8-bit PWM output 1 with programmable carrier frequency
P3.1/AOPWM2	Input/output, can be configured as 8-bit PWM output 2 with programmable carrier frequency

Crystal Interface

XTAL0	Input, connected to crystal
XTAL1	Output, connected to crystal

Reset Interface

RESET	Input and Output, system reset, doesn't require external RC time constant
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I²C Interface

SCL/SO-SI	Output, I ² C clock output, or SPI data
SDA/CS0	Input/output, I ² C Data line or SPI chip select 0

I²C/SPI Interface

SCL/SO-SI	Output, I ² C clock output, or SPI data
SDA/CS0	Input/output, I ² C data line or SPI chip select 0
P1.3/SYNC/SCK	Input/output port 1.3, can be configured as SYNC output or SPI clock output, needs to be pulled up to VDD1 in order to boot from I ² C EEPROM
P3.0/INT2/CS1	Input/output port 3.0, can be configured as INT2 input or SPI chip select 1

4.2 Motion Peripheral Interface Group

PWM

PWMUH	Output, PWM phase U high side gate signal, internally pulled down by 58kΩ
PWMUL	Output, PWM phase U low side gate signal, internally pulled down by 58kΩ
PWMVH	Output, PWM phase V high side gate signal, internally pulled down by 58kΩ
PWMVL	Output, PWM phase V low side gate signal, internally pulled down by 58kΩ
PWMWH	Output, PWM phase W high side gate signal, internally pulled down by 58kΩ
PWMWL	Output, PWM phase W low side gate signal, internally pulled down by 58kΩ

Fault

GATEKILL	Input, upon assertion, this negates all six PWM signals, active low, internally pulled up by 70kΩ
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4.3 Analog Interface Group

AVSS	Analog power return, (analog internal 1.8V power is shared with VDDCAP)
AREF	0.6V buffered output
CMEXT	Unbuffered 0.6V, input to the AREF buffer, capacitor needs to be connected.
IFB+	Input, Operational amplifier positive input for shunt resistor current sensing
IFB-	Input, Operational amplifier negative input for shunt resistor current sensing
IFBO	Output, Operational amplifier output for shunt resistor current sensing
AIN0	Input, Analog input channel 0 (0 – 1.2V), typically configured for DC bus voltage input
AIN1	Input, Analog input channel 1 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN2	Input, Analog input channel 2 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN3	Input, Analog input channel 3 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN4	Input, Analog input channel 4 (0 – 1.2V), needs to be pulled down to AVSS if unused
AIN5+	Input, Operational amplifier positive input for shunt resistor current sensing
AIN5-	Input, Operational amplifier negative input for shunt resistor current sensing
AIN5O	Output, Operational amplifier output for AIN5 output, there is a single sample/hold circuit on the output

4.4 Power Interface Group

VDD1	Digital power (3.3V)
VDDCAP	Internal 1.8V output, requires capacitors to the pin. Shared with analog power pad internally
VSS	Digital common

4.5 Test Interface Group

P5.2/TMS	JTAG test mode input or input/output digital port
TDO	JTAG data output
P5.1/TDI	JTAG data input, or input/output digital port
TCK	JTAG test clock

5 DC Characteristics

5.1 Absolute Maximum Ratings

Symbol	Parameter	Min	Typ	Max	Condition
V _{DD1}	Supply Voltage	-0.3 V	-	3.6 V	Respect to VSS
V _{IA}	Analog Input Voltage	-0.3 V	-	1.98 V	Respect to AVSS
V _{ID}	Digital Input Voltage	-0.3 V	-	6.0 V	Respect to VSS
V _{PP}	OTP Programming voltage	-0.3V	-	7.0V	Respect to VSS
T _A	Ambient Temperature	-40 °C	-	85 °C	
T _S	Storage Temperature	-65 °C	-	150 °C	

Table 1 Absolute Maximum Ratings

Caution: Stresses beyond those listed in “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and function of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied.

5.2 System Clock Frequency and Power Consumption

C_{AREF} = 1nF, C_{MEXT} = 100nF. VDD1=3.3V, Unless specified, Ta = 25 °C.

Symbol	Parameter	Min	Typ	Max	Unit
SYSCCLK	System Clock	32	-	128	MHz
P _D	Power consumption		160 ¹⁾	200	mW

Table 2 System Clock Frequency

Note 1) The value is based on the condition of MCE clock=126MHz, 8051 clock 31.5MHz with a actual motor running by a typical MCE application program and 8051 code.

5.3 Digital I/O DC Characteristics

Symbol	Parameter	Min	Typ	Max	Condition
V_{DD1}	Supply Voltage	3.0 V	3.3 V	3.6 V	Recommended
V_{PP}	OTP Programming voltage	6.70V	6.75V	6.80V	Recommended
V_{IL}	Input Low Voltage	-0.3 V	-	0.8 V	Recommended
V_{IH}	Input High Voltage	2.0 V		3.6 V	Recommended
C_{IN}	Input capacitance	-	3.6 pF	-	(1)
I_L	Input leakage current		± 10 nA	± 1 μ A	$V_O = 3.3$ V or 0 V
$I_{OL1}^{(2)}$	Low level output current	8.9 mA	13.2 mA	15.2 mA	$V_{OL} = 0.4$ V (1)
$I_{OH1}^{(2)}$	High level output current	12.4 mA	24.8 mA	38 mA	$V_{OH} = 2.4$ V (1)
$I_{OL2}^{(3)}$	Low level output current	17.9 mA	26.3 mA	33.4 mA	$V_{OL} = 0.4$ V (1)
$I_{OH2}^{(3)}$	High level output current	24.6 mA	49.5 mA	81 mA	$V_{OH} = 2.4$ V (1)

Table 3 Digital I/O DC Characteristics

Note:

- (1) Data guaranteed by design.
- (2) Applied to SCL/SO-SI, SDA/CS0 pins.
- (3) Applied to all digital I/O pins except SCL/SO-SI and SDA/CS0 pins.

5.4 PLL and Oscillator DC characteristics

$C_{AREF} = 1nF$, $C_{MEXT} = 100nF$. $VDD1=3.3V$, Unless specified, $T_a = 25^{\circ}C$.

Symbol	Parameter	Min	Typ	Max	Condition
$V_{IL\ OSC}$	Oscillator (XTAL0,1) Input Low Voltage	0	-	$0.2 * V_{DDCAP}$	V_{DDCAP} = voltage at VDDCAP pin
$V_{IH\ OSC}$	Oscillator (XTAL0,1) Input High Voltage	$0.8 * V_{DDCAP}$	-	V_{DDCAP}	V_{DDCAP} = voltage at VDDCAP pin

Table 4 PLL DC Characteristics

5.5 Analog I/O (IFB+,IFB-,IFBO, AIN5+,AIN5-,AIN5O) DC Characteristics

$C_{AREF} = 1nF$, $C_{MEXT} = 100nF$. $VDD1=3.3V$, Unless specified, $T_a = 25^{\circ}C$.

Symbol	Parameter	Min	Typ	Max	Condition
V_{OFFSET}	Input Offset Voltage	-	-	26 mV	
V_I	Input Voltage Range	0 V		1.2 V	Recommended
V_{OUTSW}	OP amp output operating range	50 mV (1)	-	1.2 V	
C_{IN}	Input capacitance	-	3.6 pF	-	(1)
R_{FDBK}	OP amp feedback resistor	5 k Ω	-	20 k Ω	Requested between IFBO and IFB-
OP_{GAINCL}	Operating Close loop Gain	80 db	-	-	(1)
CMRR	Common Mode Rejection Ratio	-	80 db	-	(1)
I_{SRC}	Op amp output source current	-	1 mA	-	$V_{OUT} = 0.6 V$ (1)
I_{SNK}	Op amp output sink current	-	100 μA	-	$V_{OUT} = 0.6 V$ (1)

Table 5 Analog I/O DC Characteristics

Note:

(1) Data guaranteed by design.

5.6 Under Voltage Lockout DC characteristics

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
UV_{CC+}	UVcc positive going Threshold	2.78 V	3.04 V	3.23 V	(1)
UV_{CC-}	UVcc negative going Threshold	2.78 V	2.97 V	3.23 V	
UV_{CCH}	UVcc Hysteresys	-	73 mV	-	(1)

Table 6 UVcc DC Characteristics

Note:

(1) Data guaranteed by design.

5.7 Itrip comparator DC characteristics

Unless specified, $V_{DD1}=3.3\text{V}$, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
I_{trip+}	Itrip positive going Threshold	-	1.22V	-	
I_{trip-}	Itrip negative going Threshold	-	1.10V	-	
I_{tripH}	Itrip Hysteresys	-	120mV	-	

Table 7 Itrip DC Characteristics

5.8 CMEXT and AREF Characteristics

$C_{AREF} = 1\text{nF}$, $C_{MEXT} = 100\text{nF}$. Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
V_{CM}	CMEXT voltage	495 mV	600 mV	700 mV	$V_{DD1} = 3.3\text{ V}^{(1)}$
V_{AREF}	Buffer Output Voltage	495 mV	600 mV	700 mV	$V_{DD1} = 3.3\text{ V}$
ΔV_o	Load regulation ($V_{DC}-0.6$)	-	1 mV	-	(1)
PSRR	Power Supply Rejection Ratio	-	75 db	-	(1)

Table 8 CMEXT and AREF DC Characteristics

Note:

(1) Data guaranteed by design.

6 AC Characteristics

6.1 Digital PLL AC Characteristics

Symbol	Parameter	Min	Typ	Max	Condition
F_{CLKIN}	Crystal input frequency	3.2 MHz	4 MHz	60 MHz	(1) (see figure below)
F_{PLL}	Internal clock frequency	32 MHz	50 MHz	128 MHz	(1)
F_{LWPW}	Sleep mode output frequency	$F_{CLKIN} \div 256$	-	-	(1)
J_S	Short time jitter	-	200 psec	-	(1)
D	Duty cycle	-	50 %	-	(1)
T_{LOCK}	PLL lock time	-	-	500 μ sec	(1)

Table 9 PLL AC Characteristics

Note:

(1) Data guaranteed by design.

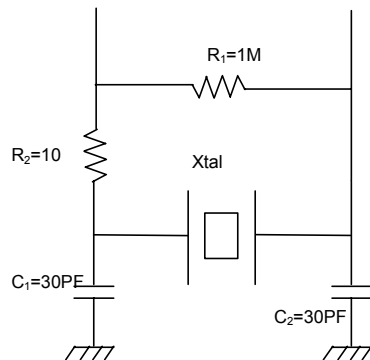


Figure 3 Crystal circuit example

6.2 Analog to Digital Converter AC Characteristics

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Condition
T_{CONV}	Conversion time	-	-	2.05 μsec	⁽¹⁾
T_{HOLD}	Sample/Hold maximum hold time	-	-	10 μsec	Voltage droop ≤ 15 LSB (see figure below)

Table 10 A/D Converter AC Characteristics

Note:

(1) Data guaranteed by design.

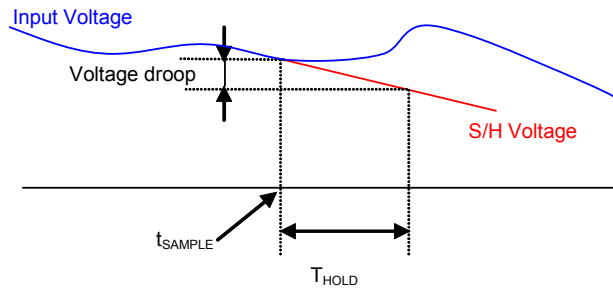


Figure 4 Voltage droop and S/H hold time

6.3 Op amp AC Characteristics

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Condition
OP _{SR}	OP amp slew rate	-	10 V/μsec	-	VDD1 = 3.3 V, CL = 33 pF ⁽¹⁾
OP _{IMP}	OP input impedance	-	10 ⁸ Ω	-	⁽¹⁾ ⁽²⁾
T _{SET}	Settling time	-	400 ns	-	VDD1 = 3.3 V, CL = 33 pF ⁽¹⁾

Table 11 Current Sensing OP Amp AC Characteristics

Note:

(1) Data guaranteed by design.

(2) To guarantee stability of the operational amplifier, it is recommended to load the output pin by a capacitor of 47pF, see Figure 5. Here only the single shunt current amplifier is show but all op amp outputs should be loaded with this capacitor.

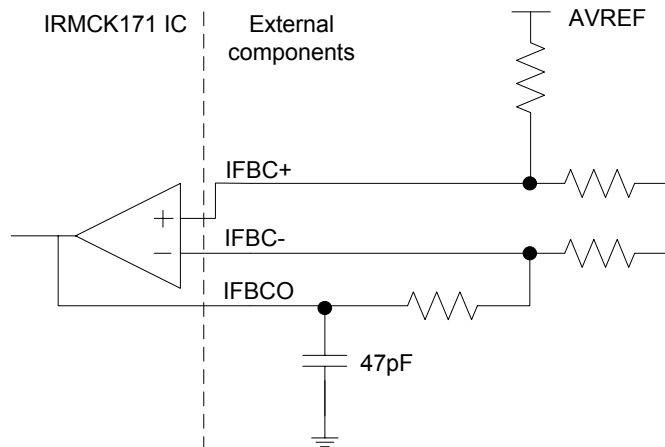


Figure 5 A capacitor of 47pF is recommended at the output pin of all op amps.

6.4 SYNC to SVPWM and A/D Conversion AC Timing

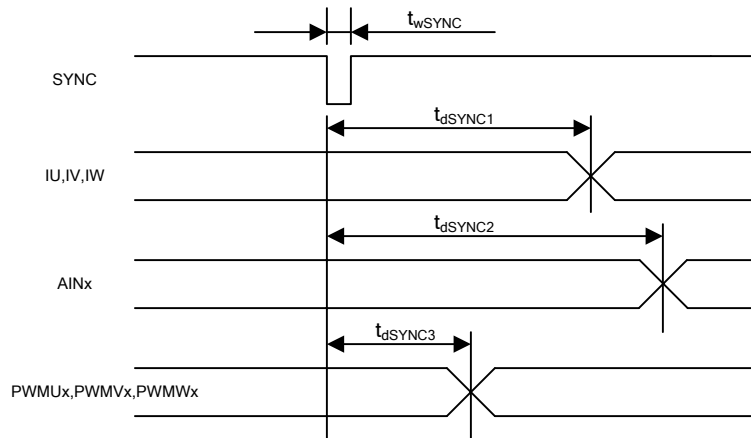


Figure 6 SYNC timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
$t_{w\text{SYNC}}$	SYNC pulse width	-	32	-	SYSClk
$t_{d\text{SYNC}1}$	SYNC to current feedback conversion time	-	-	100	SYSClk
$t_{d\text{SYNC}2}$	SYNC to AIN0-5 analog input conversion time	-	-	200	SYSClk ⁽¹⁾
$t_{d\text{SYNC}3}$	SYNC to PWM output delay time	-	-	2	SYSClk

Table 12 SYNC AC Characteristics

Note:

(1) AIN1 through AIN5 channels are converted once every 6 SYNC events

6.5 GATEKILL to SVPWM AC Timing

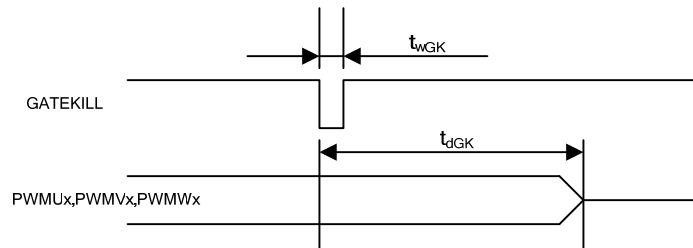


Figure 7 Gatekill timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
t_{WGK}	GATEKILL pulse width	32	-	-	SYCLK
t_{dGK}	GATEKILL to PWM output delay	-	-	100	SYCLK

Table 13 GATEKILL to SVPWM AC Timing

6.6 Itrip AC Timing

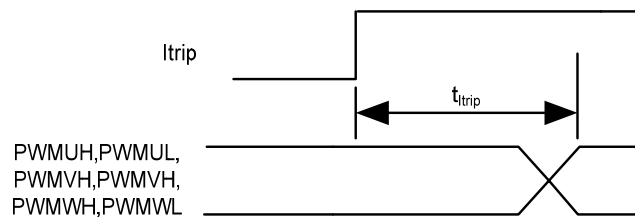


Figure 8 ITRIP timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
t_{ITRIP}	Itrip propagation delay	-	-	100(sysclk)+1.0usec	SYCLK+usec

Table 14 Itrip AC Timing

6.7 Interrupt AC Timing

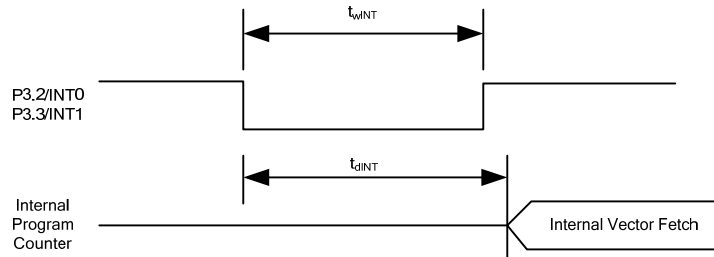


Figure 9 Interrupt timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
t_{WINT}	INT0, INT1 Interrupt Assertion Time	4	-	-	SYSCLK
t_{dINT}	INT0, INT1 latency	-	-	4	SYSCLK

Table 15 Interrupt AC Timing

6.8 I²C AC Timing

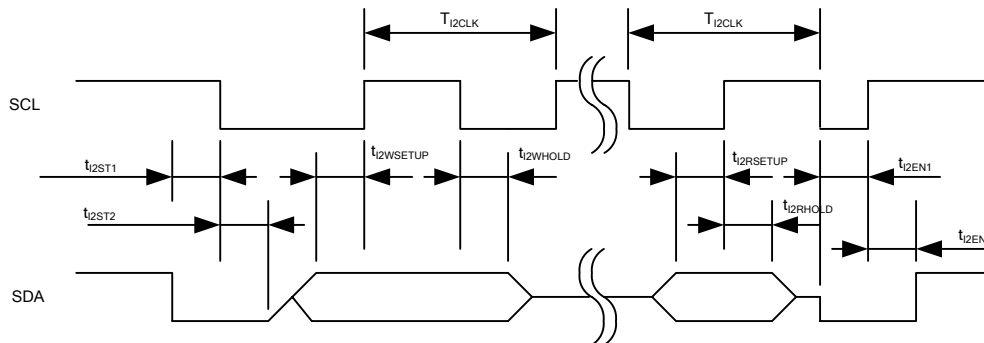


Figure 10 I²C Timing

Unless specified, Ta = 25°C.

Symbol	Parameter	Min	Typ	Max	Unit
T_{I2CLK}	I ² C clock period	10	-	8192	SYSCLK
t_{I2ST1}	I ² C SDA start time	0.25	-	-	T_{I2CLK}
t_{I2ST2}	I ² C SCL start time	0.25	-	-	T_{I2CLK}
$t_{I2WSETUP}$	I ² C write setup time	0.25	-	-	T_{I2CLK}
$t_{I2WHOLD}$	I ² C write hold time	0.25	-	-	T_{I2CLK}
$t_{I2RSETUP}$	I ² C read setup time	I ² C filter time ⁽¹⁾	-	-	SYSCLK
$t_{I2RHOLD}$	I ² C read hold time	1	-	-	SYSCLK

Table 16 I²C AC Timing

Note:

(1) I²C read setup time is determined by the programmable filter time applied to I²C communication.

6.9 SPI AC Timing

SPI Write AC timing

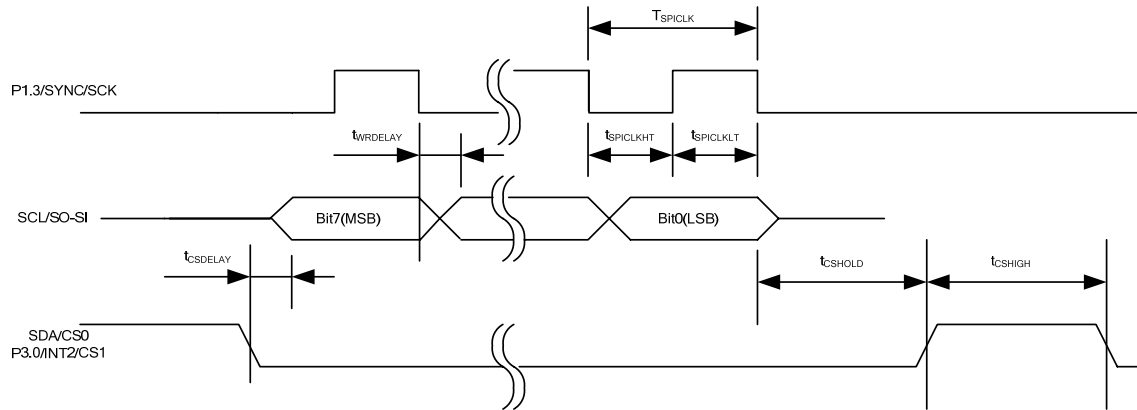


Figure 11 SPI write timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{SPICLK}	SPI clock period	4	-	-	SYSCLK
t_{SPICLKHT}	SPI clock high time	-	1/2	-	T_{SPICLK}
t_{SPICLKLT}	SPI clock low time	-	1/2	-	T_{SPICLK}
t_{CSDELAY}	CS to data delay time	-	-	10	nsec
t_{WRDELAY}	CLK falling edge to data delay time	-	-	10	nsec
t_{CSHIGH}	CS high time between two consecutive byte transfer	1	-	-	T_{SPICLK}
t_{CSHOLD}	CS hold time	-	1	-	T_{SPICLK}

Table 17 SPI Write AC Timing

SPI Read AC Timing

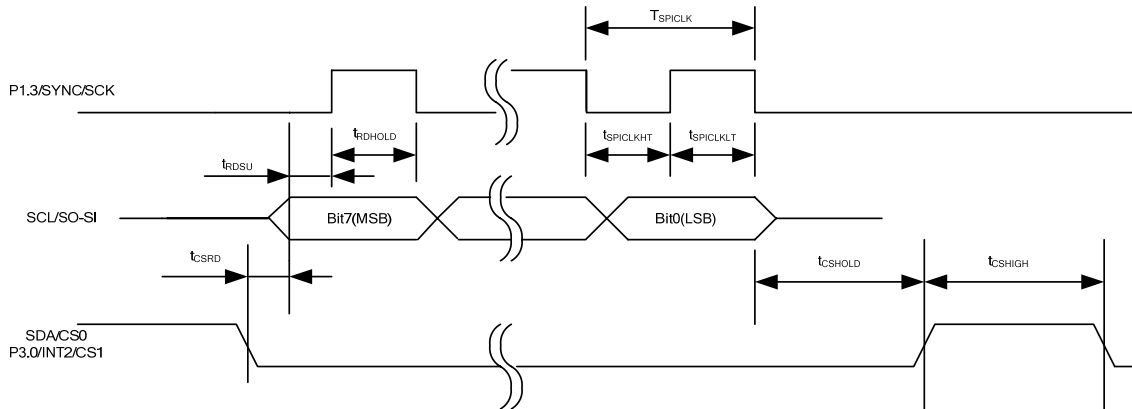


Figure 12 SPI read timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{SPICLK}	SPI clock period	4	-	-	SYSClk
$t_{SPICLKHT}$	SPI clock high time	-	1/2	-	T_{SPICLK}
$t_{SPICLKLT}$	SPI clock low time	-	1/2	-	T_{SPICLK}
t_{CSRd}	CS to data delay time	-	-	10	nsec
t_{RDSU}	SPI read data setup time	10	-	-	nsec
t_{RDHOLD}	SPI read data hold time	10	-	-	nsec
t_{CSHIGH}	CS high time between two consecutive byte transfer	1	-	-	T_{SPICLK}
t_{CSHOLD}	CS hold time	-	1	-	T_{SPICLK}

Table 18 SPI Read AC Timing

6.10 UART AC Timing

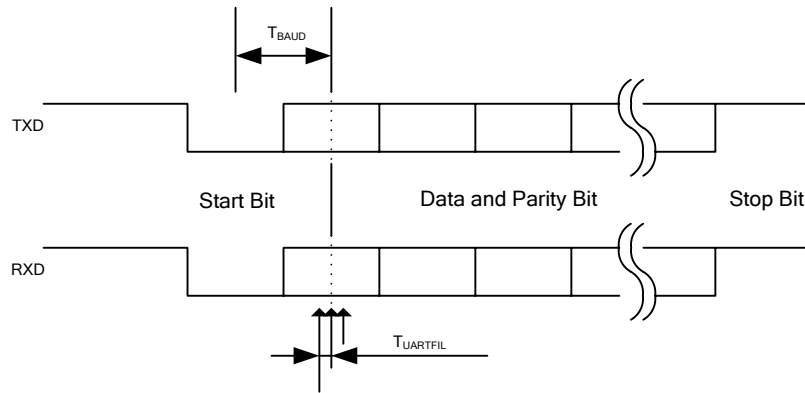


Figure 13 UART timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{BAUD}	Baud Rate Period	-	57600	-	bit/sec
$T_{UARTFIL}$	UART sampling filter period ⁽¹⁾	-	1/16	-	T_{BAUD}

Table 19 UART AC Timing

Note:

- (1) Each bit including start and stop bit is sampled three times at center of a bit at an interval of $1/16 T_{BAUD}$. If three sampled values do not agree, then UART noise error is generated.

6.11 CAPTURE Input AC Timing

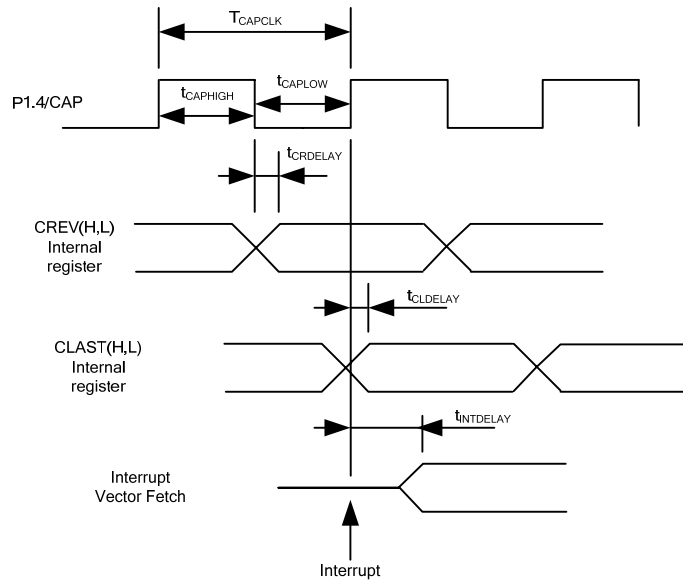


Figure 14 CAPTURE timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{CAPCLK}	CAPTURE input period	8	-	-	SYSCCLK
$t_{CAPHIGH}$	CAPTURE input high time	4	-	-	SYSCCLK
t_{CAPLOW}	CAPTURE input low time	4	-	-	SYSCCLK
$t_{CRDELAY}$	CAPTURE falling edge to capture register latch time	-	-	4	SYSCCLK
$t_{CLDELAY}$	CAPTURE rising edge to capture register latch time	-	-	4	SYSCCLK
$t_{INTDELAY}$	CAPTURE input interrupt latency time	-	-	4	SYSCCLK

Table 20 CAPTURE AC Timing

6.12 OTP Programming Timing

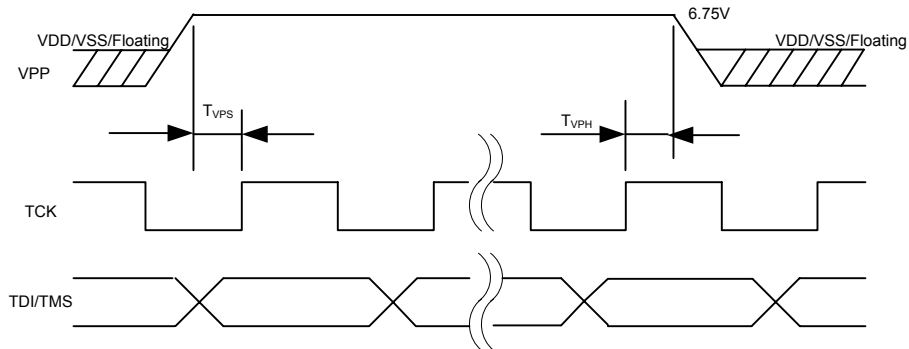


Figure 15 OTP programming timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{VPS}	VPP Setup Time	10	-	-	nsec
T_{VPH}	VPP Hold Time	15	-	-	nsec

Table 21 OTP Programming Timing

6.13 JTAG AC Timing

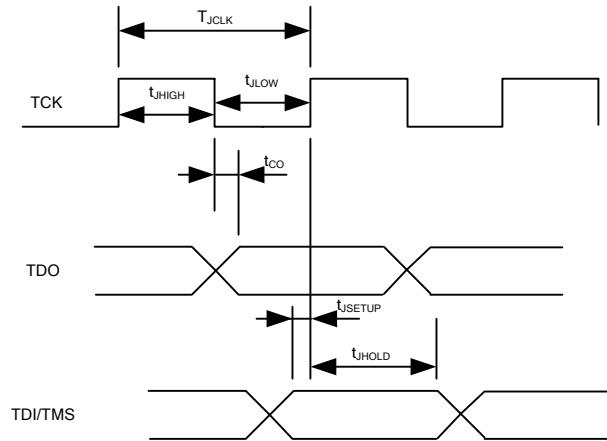


Figure 16 JTAG timing

Unless specified, $T_a = 25^\circ\text{C}$.

Symbol	Parameter	Min	Typ	Max	Unit
T_{JCLK}	TCK Period	-	-	50	MHz
t_{JHIGH}	TCK High Period	10	-	-	nsec
t_{JLOW}	TCK Low Period	10	-	-	nsec
t_{CO}	TCK to TDO propagation delay time	0	-	5	nsec
t_{JSETUP}	TDI/TMS setup time	4	-	-	nsec
t_{JHOLD}	TDI/TMS hold time	0	-	-	nsec

Table 22 JTAG AC Timing

7 I/O Structure

The following figure shows the motor PWM output (PWMUH/PWMUL/PWMVH/PWMVL/PWMWH/PWMWL)

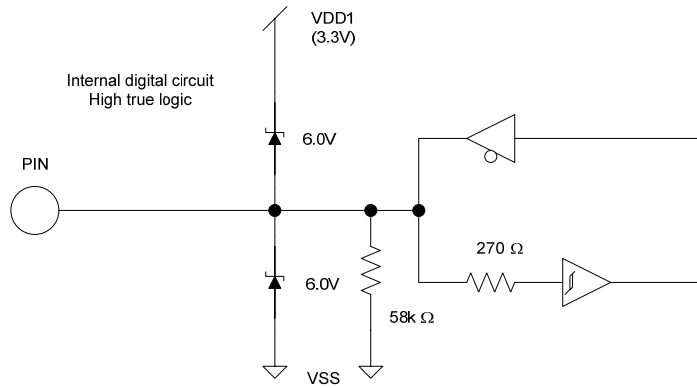


Figure 17 PWMUL/PWMUH/PWMVL/PWMVH/PWMWL/PWMWH output

The following figure shows the digital I/O structure except the motor PWM output

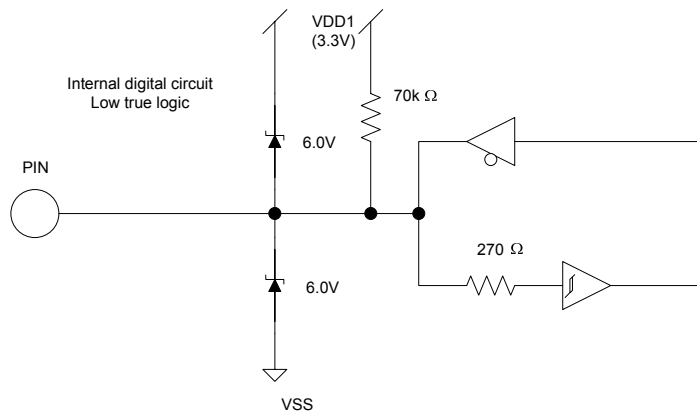


Figure 18 All digital I/O except motor PWM output

The following figure shows RESET and GATEKILL I/O structure.

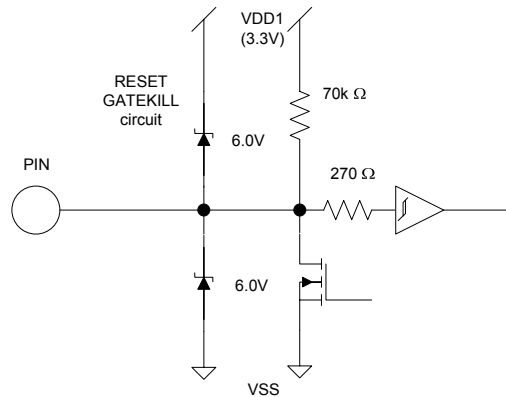


Figure 19 RESET, GATEKILL I/O

The following figure shows the analog input structure.

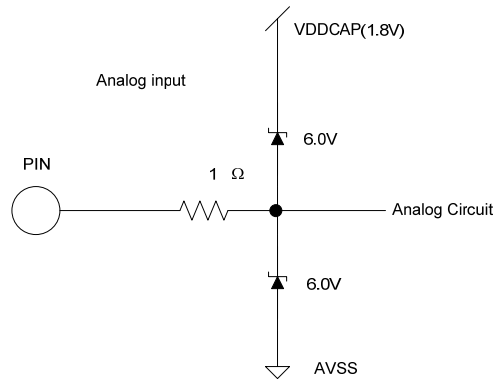


Figure 20 Analog input

The following figure shows all analog operational amplifier output pins and AREF pin I/O structure.

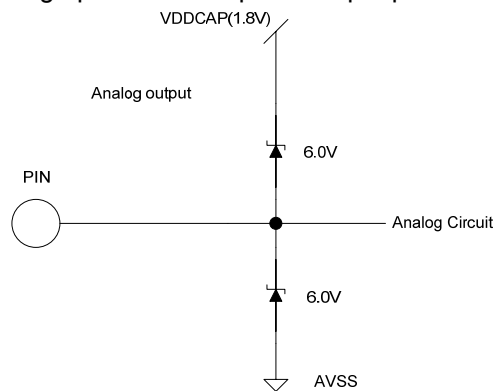


Figure 21 Analog operational amplifier output and AREF I/O structure

The following figure shows the VPP pin structure

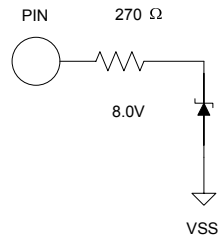


Figure 22 VPP programming pin I/O structure

The following figure shows the VSS and AVSS pins structure

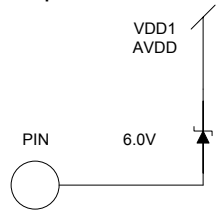


Figure 23 VSS and AVSS pin structure

The following figure shows the VDD1 and VDDCAP pin structure

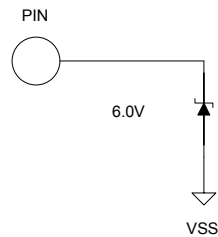


Figure 24 VDD1 and VDDCAP pin structure

The following figure shows the XTAL0 and XTAL1 pins structure

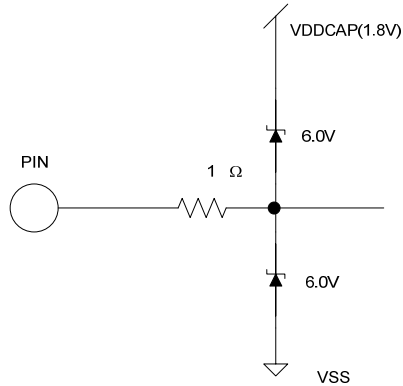


Figure 25 XTAL0/XTAL1 pins structure

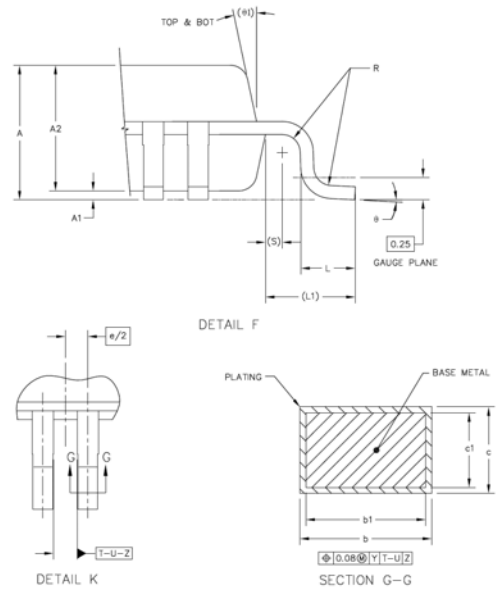
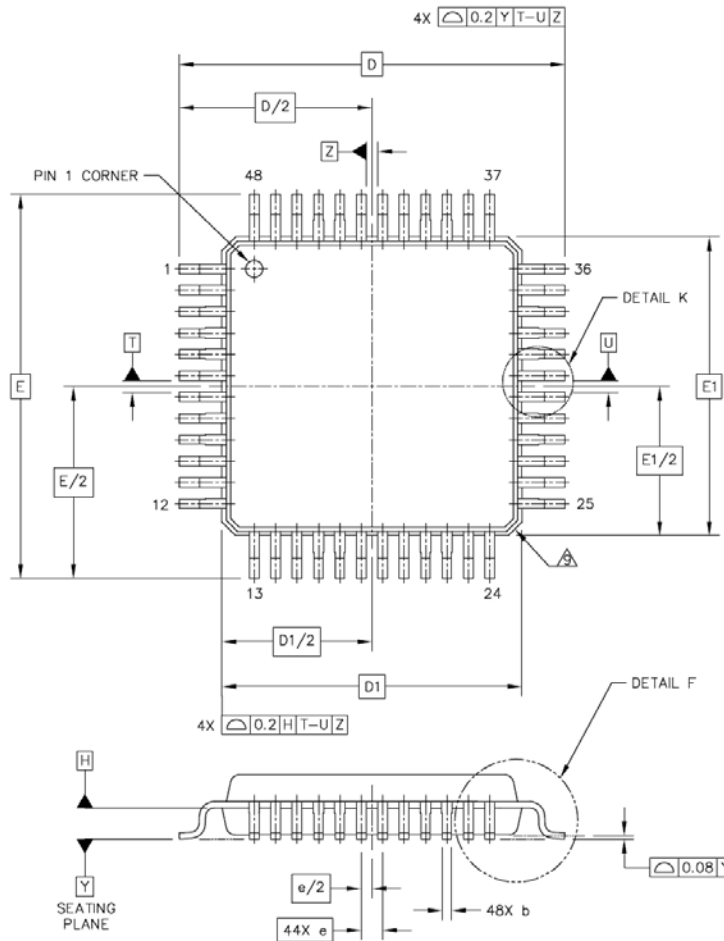
8 Pin List

Pin Number	Pin Name	Internal Pull-up /Pull-down	Pin Type	Description
1	XTAL0		I	Crystal input
2	XTAL1		O	Crystal output
3	P1.0/T2		I/O	Discrete programmable I/O or Timer/Counter 2 input
4	SCL/SO-SI		I/O	I ² C clock output (open drain, need pull up) or SPI data
5	SDA/CS0		I/O	I ² C data (open drain, need pull up) or SPI Chip Select 0
6	P1.3/SYNC/SCK		I/O	Discrete programmable I/O or SYNC output or SPI clock output, needs to be pulled up to VDD1 in order to boot from I ² C EEPROM
7	P1.4/CAP		I/O	Discrete programmable I/O or Capture timer input
8	VDD1		P	3.3V digital power
9	VSS		P	Digital common
10	VDDCAP		P	Internal 1.8V output, Capacitor(s) to be connected
11	P2.0/NMI		I/O	Discrete programmable I/O or Non-maskable Interrupt input
12	P3.2/INT0		I/O	Discrete programmable I/O or Interrupt 0 input
13	P2.7/AOPWM1		I/O	Discrete programmable I/O or PWM 1 digital output
14	AIN0		I	Analog input channel 0, 0-1.2V range, needs to be pulled down to AVSS if unused
15	AIN1		I	Analog input channel 1, 0-1.2V range, needs to be pulled down to AVSS if unused
16	AIN2		I	Analog input channel 2, 0-1.2V range, needs to be pulled down to AVSS if unused
17	AIN3		I	Analog input channel 3, 0-1.2V range, needs to be pulled down to AVSS if unused
18	AIN4		I	Analog input channel 4, 0-1.2V range, needs to be pulled down to AVSS if unused
19	IFB-		I	Single shunt current sensing OP amp input (-)
20	IFB+		I	Single shunt current sensing OP amp input (+)
21	IFBO		O	Single shunt current sensing OP amp output
22	CMEXT		O	Unbuffered 0.6V output. Capacitor needs to be connected.
23	AREF		O	Analog reference voltage output (0.6V)
24	AIN5-		I	Analog input channel 5, 0-1.2V range, needs to be pulled down to AVSS if unused
25	AIN5+		I	Analog input channel 5, 0-1.2V range, needs to be pulled down to AVSS if unused
26	AIN5O		O	Analog output 5, 0-1.2V range,
27	AVSS		P	Analog common
28	VDDCAP		P	Internal 1.8V output, Capacitor(s) to be connected
29	VDD1		P	3.3V digital power
30	VSS		P	Digital common
31	P3.1/AOPWM2		I/O	Discrete programmable I/O or PWM 2 digital output
32	PWMWL	58 kΩ Pull down	O	PWM gate drive for phase W low side, configurable either high or low true.

Pin Number	Pin Name	Internal Pull-up /Pull-down	Pin Type	Description
33	PWMVL	58 kΩ Pull down	O	PWM gate drive for phase V low side, configurable either high or low true
34	PWMUL	58 kΩ Pull down	O	PWM gate drive for phase U low side, configurable either high or low true
35	PWMWH	58 kΩ Pull down	O	PWM gate drive for phase W high side, configurable either high or low true
36	PWMVH	58 kΩ Pull down	O	PWM gate drive for phase V high side, configurable either high or low true
37	PWMUH	58 kΩ Pull down	O	PWM gate drive for phase U high side, configurable either high or low true
38	P1.5/VPP		I/O P	OTP programming power (6.5V) or Discrete programmable I/O.
39	GATEKILL	70 kΩ Pull up	I	PWM shutdown input, 2-μsec digital filter, configurable either high or low true.
40	P3.0/INT2/CS1	70 kΩ Pull up	I/O	Discrete programmable I/O or external interrupt 2 input or SPI Chip Select 1
41	P5.2/TMS		I/O	JTAG test mode select or Discrete I/O
42	TDO		O	JTAG test data output
43	P5.1/TDI		I/O	JTAG test data input or Discrete I/O
44	TCK		I	JTAG test clock
45	RESET		I/O	Reset, low true, Schmitt trigger input
46	P1.1/RXD		I/O	UART receiver input or Discrete programmable I/O
47	P1.1/RXD		I/O	UART transmitter output or Discrete programmable I/O
48	P3.3/INT1		I/O	Interrupt 1 input or Discrete I/O

Table 23 Pin List

9 Package Dimensions

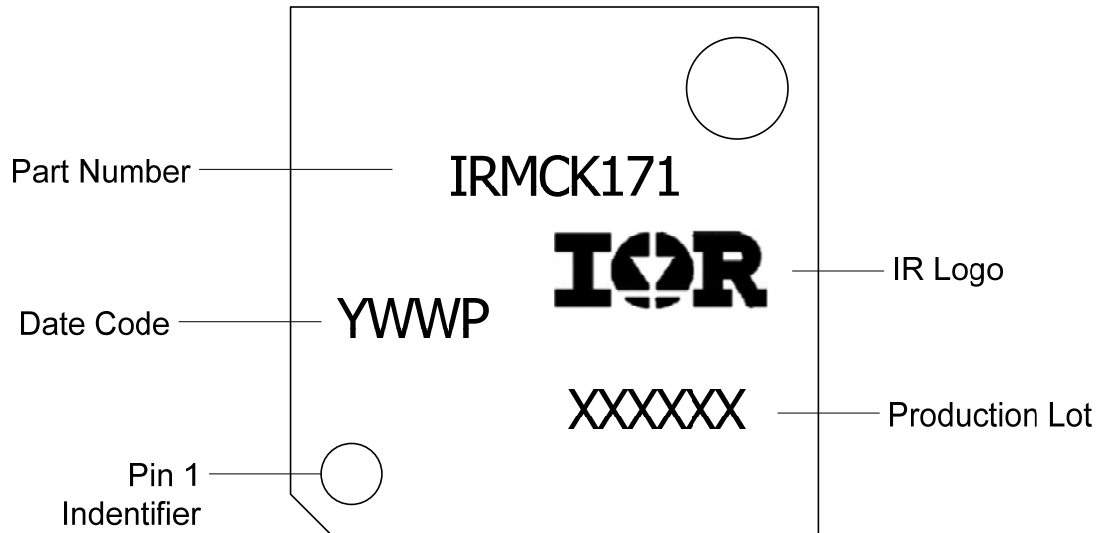


NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
 3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
 4. DATUM T, U AND Z TO BE DETERMINED AT DATUM PLANE H.
 5. DIMENSIONS D AND E TO BE DETERMINED AT SEATING PLANE Y.
 6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS D1 AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
 7. DIMENSION b DOES NOT INCLUDE DAM BAR PROTRUSION. DAM BAR PROTRUSION SHALL NOT CAUSE THE b DIMENSION TO EXCEED 0.35.
 8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.
- △ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

DIM	MIN	MAX	DIM	MIN	MAX	DIM	MIN	MAX
A	1.4	1.6	L1	1 REF				
A1	0.05	0.15	R	0.15	0.25			
A2	1.35	1.45	S	0.2 REF				
b	0.17	0.27	θ	1°	5°			
b1	0.17	0.23	θ1	12° REF				
c	0.09	0.2						
c1	0.09	0.16						
D		9 BSC						
D1		7 BSC						
e		0.5 BSC						
E		9 BSC						
E1		7 BSC						
L	0.5	0.7						

10 Part Marking Information



International
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